

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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EPAS ID: PAT4355317

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
IKUROH ICHITSUBO	08/09/2004
WEIPING WANG	08/09/2004
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<b>Property Type</b>	<b>Number</b>
Patent Number:	7071783
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<b>SIGNATURE:</b>	/Christopher J. Horgan/
<b>DATE SIGNED:</b>	04/05/2017
<b>Total Attachments: 2</b>	
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## ASSIGNMENT OF PATENT APPLICATION

WHEREAS, INVENTORS Ikuroh Ichitsubo of Sagamihara, Japan, and Weiping Wang of Palo Alto, California, hereinafter referred to as "Assignor," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: TEMPERATURE COMPENSATED POWER SENSING CIRCUIT FOR POWER AMPLIFIERS

Filing Date: Herewith

Application No.: N/A; and

WHEREAS, Micro Mobio Corporation, located at 2275 East Bayshore Road, Suite 101, Palo Alto, CA 94303, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignor had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees that he will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

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IN TESTIMONY WHEREOF, Assignor has signed his name on the date indicated.

Dated: Aug. 9, 2004



Ikuroh Ichitsubo

Dated: Aug 9, 2004



Weiping Wang

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